

Patent Abstracts of Japan

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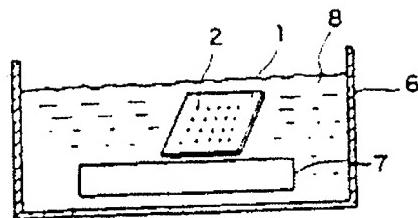
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TITLE : METHOD OF CLEANING INSIDE OF
HOLE OF PRINTED BOARD



ABSTRACT : PURPOSE: To make it possible to fully eject chips remaining inside through holes of a printed board regardless of the aspect ratio by immersing a printed board in which through holes are pierced, in a stored cleaning solution and by causing ultrasonic vibration in the solution.

CONSTITUTION: Through holes 2 are pierced in a printed board 1. To clean the insides of the holes of the printed board 1, that is, to eject chips remaining inside the through holes, the printed board 1 in which said through holes 2 are pierced is immersed in a stored cleaning solution 8, and by ultrasonic-vibrating the solution 8, the chips inside the through holes 2 are ejected. For example, the printed board 1 in which the through hole 2 is pierced by, for example, drilling, is immersed in a liquid vessel 6. In that case, to make the direction of the through hole 2 vertical, the printed board 1 is preferably mounted horizontally. When an ultrasonic wave generating equipment 7 is started, water 8 is vibrated by the ultrasonic wave. The chip remaining in the through holes 2 are vibrated together with the water 8, and they are all ejected from the through hole 2.

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